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MEMS Prototyping



In addition to SOI, BCD, CMOS, BiCMOS, SiGe and Silicon Photonic Integrated Circuits Integrated, bulk micromachining technologies and specific surface micromachining technologies are available through CMP.

CMP distributes Process Design-Kits (PDK) for CMOS/BiCMOS IC's, Photonic IC's and MEMS' technologies. Each of them contains technology files, simulation models, design rules, standard cell libraries. A copy of any requested design kit can be sent to the customer after a non-disclosure agreement (NDA) with CMP.

Customer request and support are provided through our Web interfaces:

Design-Kit Request Form -> <http://mycmp.fr/requests/design-kit-dk>

Design-Kit Support Center: <http://mycmp.fr/requests/support>

Contact us

Request Form: S. EYRAUD [Sylvain.e.yraud@mycmp.fr]

Support Center: Ch. RABACHE [Christelle.Rabache@mycmp.fr]

ams 0.35µm CMOS Bulk Micromachining



Front-side
Bulk Micromachining
Suspended Beams

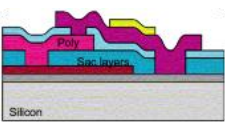
Based on standard ams CMOS or BiCMOS process, this technology allows integration of MEMS sensor and front-end electronic on the same die for integration and better signal to noise ratio. Suspended passive devices or structures can be made with this technology. Applications include thermal, inertial and infrared sensors.

ams 0.35µm CMOS Bulk Micromachining:
Front-side or Back-side: price under request.

MEMSCAP: PolyMUMPS - SOIMUMPS - PiezoMUMPS

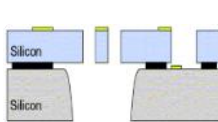
Allows the realization of various MEMS devices: 3900€ for 15 identical chips, (1mm x 1mm, fixed size).

PolyMUMPS



Polysilicon/gold surface micromachining

SOIMUMPS

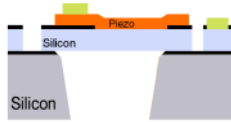


Deep reactive ion etching on silicon on insulator



SoiMUMPS_SEM view

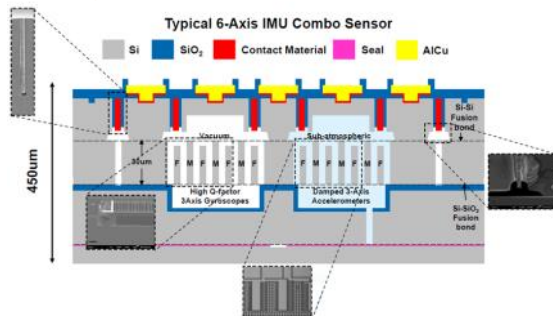
PiezoMUMPS



SOIMUMPS + piezoelectric layer

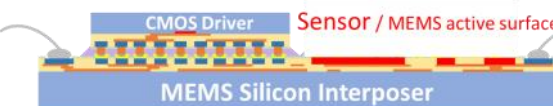
On-chip suspended membrane with piezo resistors

Teledyne DALSA TDSI MIDIS™



MIDIS™ MEMS technology is offered to CMP user community thanks to an agreement and partnership with CMC, Canada. The MEMS Integrated Design for Inertial Sensors (MIDIS™) platform is designed to provide a standard process for manufacturing accelerometers and gyroscopes: 8000€ (4mm x 4mm).

Packaging



- Optical resin
- Chip On Board (COB)
- Thermal solutions
- Metallic package
- Hermetic sealing
- Hybrid packaging MEMS / Si Photonics + CMOS

- Minimum charges apply on most MPW services (invoice of a minimum surface).
- Digestive prices are applied to most MPW services.
- Prices may change without notice. Check on the Web site.

Contact us

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Partnership:



Sept-17

